



PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Salman Akram

Serial No.: 10/033,233

Filed: December 28, 2001

For: CHIP PACKAGE WITH GREASE
HEAT SINK AND METHOD OF MAKING

Confirmation No.: 9685

Examiner: K. Nguyen

Group Art Unit: 2823

Attorney Docket No.: 2269-6890.1US
(99-0439.01/US)

Notice of Allowance Mailed:

January 26, 2005

NOTICE OF EXPRESS MAILING

Express Mail Mailing Label Number: EL994848781US

Date of Deposit with USPS: April 26, 2005

Person making Deposit: Steven P. Wong

TRANSMITTAL LETTER

Mail Stop ISSUE FEE
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

Applicant submits herewith Part B - Fee(s) Transmittal for the above-captioned application and a check in the amount of \$1715.00 in payment therefor plus five (5) copies of the patent when issued.

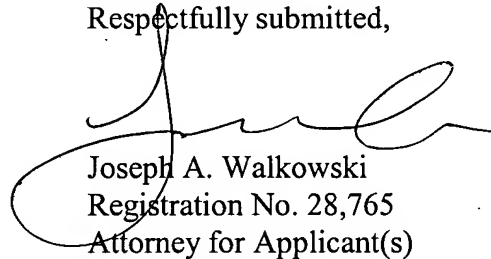
Also, enclosed herewith are the following documents:

1. Amendment Pursuant to 37 C.F.R. § 1.312(a);

2. Annotated sheets showing changes made (12 sheets);
3. Replacement formal drawings (4 sheets);
4. Comments on Statement of Reasons for Allowance (2 pages);
5. Fee Addressee for Receipt of PTO Notices Relating to Maintenance Fees; and
6. Power of Attorney (37 C.F.R. § 1.34 (a)), Revocation of Prior Power of Attorney (37 C.F.R. § 1.33 (d)) and Request to Change Correspondence Address (37 C.F.R. § 1.33 (d)) with Statement Pursuant to 37 C.F.R. § 3.73.

Applicant understands that no additional fees are required. However, if the Office determines that any comparison fees or other additional fees are required, the Commissioner is authorized to charge any such fees to TraskBritt Deposit Account No. 20-1469. A copy of this Transmittal Letter is enclosed for deposit account charging purposes.

Respectfully submitted,



Joseph A. Walkowski
Registration No. 28,765
Attorney for Applicant(s)
TRASKBRITT
P.O. Box 2550
Salt Lake City, Utah 84110-2550
Telephone: 801-532-1922

Date: April 26, 2005
JAW/djp:slm

Enclosures: Part B - Fee(s) Transmittal
Check No. 7731 in the amount of \$1715.00
Copy of Transmittal Letter
Amendment Pursuant to 37 C.F.R. § 1.312(a)
Annotated sheets showing changes made (12 sheets)
Replacement formal drawings (4 sheets)
Comments on Statement of Reasons for Allowance (2 pages)
Fee Addressee for Receipt of PTO Notices Relating to Maintenance Fees (2 pages)
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COMMENTS ON STATEMENT OF REASONS FOR ALLOWANCE

Mail Stop Issue Fee
Commissioner for Patents
PO Box 1450
Alexandria, VA 22313-1450

Sir:

The Examiner indicates:

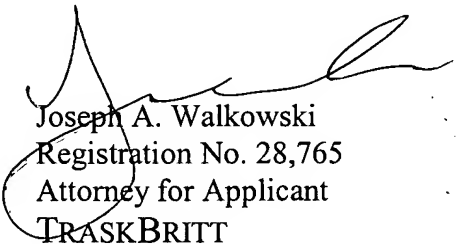
[(See Applicant's Amendment and Response submitted on May 17th, 2004, on page 8, lines 3-12)]

The prior art taken alone or in combination neither discloses nor makes obvious the instant process of claims as a whole. Specifically, the prior art of record, Mu (U.S. Patent 4,887,148) discloses a method of making an IC chip package having an IC chip with an active surface, the active surface having extending therefrom an electrical connector in electrical communication with IC chip, the IC chip being mounted upon a substrate, the method comprising (col. 3, line 4 to col. 4, line 15 and FIGS. 1-5): providing a container (FIG. 1: 22, 52) disposed upon the

substrate, the container in contact with the active surface of the IC chip (FIG. 1: 18); and injecting a grease (FIG. 1: 20) in contact with the active surface of the IC chip such that the grease is enclosed by the container and the substrate (col. 5, lines 10-33); and is in contact with the active surface and the electrical connector (FIG. 1: 44) but fails to teach or suggest the Applicant's steps of providing a second IC chip having an active surface and being disposed over the first side of the BOC substrate; providing a container disposed upon the BOC substrate, the container in contact with the active surface of the first IC chip; and inject a grease between the BOC substrate and the containers as recited in the independent claim 16, lines 6-10.]

Applicant concurs with the reasons as stated by the Examiner insofar as they comprise a summary, and are exemplary and not limiting. However, the scope of the claims must be determined from the literal language of each as a whole, as well as equivalents thereof.

Respectfully submitted,



Joseph A. Walkowski
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Date: April 26, 2005
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Document in ProLaw